

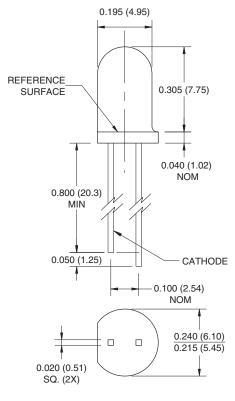
QSD2030F Plastic Silicon Photodiode

Features

- PIN Photodiode
- Package type: T-1 3/4 (5mm lens diameter)
- Wide Reception Angle, 40°

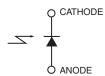
- Daylight Filter
- Package material and color: Black epoxy
- High Sensitivity
- Peak Sensitivity $\lambda = 880 \text{ nm}$

Package Dimensions





Schematic



NOTES:

- Dimensions for all drawings are in inches (mm).
- Tolerance of ± .010 (.25) on all non-nominal dimensions unless otherwise specified.

Absolute Maximum Ratings (T_A = 25°C unless otherwise specified)

Parameter	Symbol	Rating	Unit
Operating Temperature	T _{OPR}	-40 to +100	°C
Storage Temperature	T _{STG}	-40 to +100	°C
Soldering Temperature (Iron) ^(2,3,4)	T _{SOL-I}	240 for 5 sec	°C
Soldering Temperature (Flow) ^(2,3)	T _{SOL-F}	260 for 10 sec	°C
Reverse Breakdown Voltage	V _{BR}	50	V
Power Dissipation ⁽¹⁾	P _D	100	mW

Electrical/Optical Characteristics (T_A =25°C)

Parameter	Test Conditions	Symbol	Min	Тур	Max	Units
Peak Sensitivity Wavelength		λ _{PS}	_	880	_	nm
Wavelength Sensitivity Range		λ_{SR}	700	_	1100	nm
Reception Angle		Θ	_	±20	_	Deg.
Forward Voltage	I _F = 80 mA	V _F	_	1.3	_	V
Reverse Dark Current	V _R = 20 V, Ee = 0	I _D	_	_	5	nA
Reverse Light Current	Ee = 0.5 mW/cm ² , $V_R = 5 V$, $\lambda = 950 nm$	ΙL	15	25		μA
Capacitance	V _R = 0, f = 1 MHz, Ee = 0	С	_	60	_	pF
Rise Time	$V_R = 5 \text{ V}, R_L = 50 \Omega$	t _r	_	5	_	ns
Fall Time	$\lambda = 950 \text{ nm}$	t _f	_	5	_	

Notes:

- 1. Derate power dissipation linearly 1.33 mW/°C above 25°C.
- 2. RMA flux is recommended.
- 3. Methanol or isopropyl alcohols are recommended as cleaning agents.
- 4. Soldering iron 1/16" (1.6mm) minimum from housing.

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